

#5
Formal drawings
J. White

PATENT RECEIVED
4-MAR-26 2002
TC 2800 MAIL ROOM

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hui et al.

Serial No.: 09/916,197

Filed: July 26, 2001

For: METHOD FOR ENCAPSULATING
INTERMEDIATE CONDUCTIVE
ELEMENTS CONNECTING A
SEMICONDUCTOR DIE TO A
SUBSTRATE AND SEMICONDUCTOR
DEVICES SO PACKAGED

Examiner: Unknown

Group Art Unit: 2841

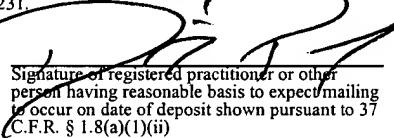
Attorney Docket No.: 4712US (99-1054)



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TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

Attached please find the formal drawings for this application.

Respectfully submitted,



Brick G. Power
Registration No. 38,581
Attorney for Applicants
TRASKBRITT
P. O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: (801) 532-1922

Date: March 13, 2002
BGP/dlm